

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1. (Currently Amended) An electronic component comprising a package having a stepped level-difference in ~~the~~an inner wall, a plurality of internal contact electrodes provided on ~~the~~an upper end-surface of said stepped level-difference in the inner wall, a shield electrode provided at ~~the~~an inner bottom surface of said package, a chip mounted on the shield electrode, and an interconnection wire for connecting the chip and said internal contact electrode; wherein

a non-electrode portion is provided, which region is used for determining a place for at least one either mounting said chip on said inner bottom surface or bonding said interconnection wire on said internal contact electrode.

2. (Original) An electronic component comprising a ceramic substrate; a first ceramic frame body formed on one of the surfaces of said ceramic substrate; a second ceramic frame body formed on said first ceramic frame body; steps formed by said ceramic substrate and said first ceramic frame body and by said first ceramic frame body and said second ceramic frame body; an internal contact electrode formed on the main surface of said first ceramic frame body at the same side as a junction formed by said first ceramic frame body and said second ceramic frame body, which internal contact electrode extending as far as the other surface of said ceramic substrate covering the side faces of said first ceramic frame body and said ceramic substrate; a shield electrode formed on the one surface of said ceramic substrate for having a chip mounted thereon, the chip is being mounted on said shield electrode; and an interconnection wire for connecting said chip and said internal contact electrode; wherein

a non-electrode portion is provided, which region is used for determining a place for at least one either mounting said chip on said ceramic substrate or bonding said interconnection wire on said internal contact electrode.

3. (Previously Presented) The electronic component of claim 1, wherein said non-electrode portion is provided for at least two, and said chip is disposed on said shield electrode in a place connecting said two non-electrode portion .

4. (Previously Presented) The electronic component of claim 1, wherein one of the sides of said non-electrode portion substantially and one of the sides of said internal contact electrode substantially coincide on a straight line.

5. (Previously Presented) The electronic component of claim 1, wherein one of the sides of said internal contact electrode and one of the sides of said non-electrode portion cross at substantially a right angle, as viewed from the above.

6. (Previously Presented) The electronic component of claim 1, wherein clearance between the stepped level-differences in the package's inner wall surface is greater in the lower part than in the upper part.

7. (Previously Presented) The electronic component of claim 1, wherein the upper surfaces of internal contact electrode and chip are substantially on a same plane.

8. (Previously Presented) The electronic component of claim 1, wherein the length of a non-shielded electrode portion along a direction connecting the internal contact electrode and the chip is greater than the value of focus shift margin of a lens used for recognizing a boundary between said internal contact electrode and non-shielded electrode portion.

9. (Previously Presented) The electronic component of claim 1, wherein a side, facing the internal contact electrode, of the non-shielded electrode portion has a length that is greater than the value of a gap between the internal contact electrodes.

10. (Original) A method for manufacturing electronic components comprising:

a first step for mounting a chip in a package provided with a stepped level-difference in the opposing inner walls and a plurality of internal contact electrodes formed on the upper surface of said stepped level-difference;

a second step for detecting a boundary formed by said stepped level-difference and the inner bottom surface of said package for at least two, and determining, based on results of the detection, a spot for connecting said internal contact electrode and said chip with an interconnection wire;

a third step for electrically connecting said chip and said internal contact electrode with said interconnection wire; and

a fourth step for sealing an opening of said package with a lid.

11. (Original) The method for manufacturing electronic components recited in claim 10, which electronic components having a shield electrode on the inner bottom surface of the package and a non-shielded electrode portion which is disposed in an arrangement where one of the sides, or the extension, crosses with one of the sides of said internal contact electrode, or the extension, at a right angle as viewed from above said package; in the first step wherein,

a spot for bonding the interconnection wire is determined by detecting a cross point formed by one of the sides of said non-shielded electrode portion, or the extension, and one of the sides of said internal contact electrode, or the extension, for at least two.

12. (Original) A method for manufacturing electronic components comprising:

a first step for determining a place for mounting a chip in a package provided with a stepped level-difference in the opposing inner walls and a plurality of internal contact electrodes formed on the upper surface of the stepped level-difference, based on results of a detection conducted to recognize a boundary formed by said stepped level-difference and inner bottom surface for at least two, as viewed from above the package;

a second step for mounting said chip on the inner bottom surface of said package;

a third step for electrically connecting said chip and said internal contact electrode with an interconnection wire; and

a fourth step for sealing an opening of said package with a lid.

13. (Original) The method for manufacturing electronic components recited in claim 12, which electronic components having a shield electrode on the inner bottom surface of the package and a non-shielded electrode portion, which region is disposed in an arrangement where one of the sides, or the extension, crosses with one of the sides of said internal contact electrode, or the extension, at a right angle as viewed from above said package; in the first step wherein,

a place for mounting the chip is determined by detecting a cross point formed by one of the sides of said non-shielded electrode portion, or the extension, and one of the sides of said internal contact electrode, or the extension, for at least two.

14. (Original) A method for manufacturing electronic components comprising:

a first step for determining a place for mounting a chip in a package provided with a stepped level-difference in the opposing inner walls and a plurality of internal contact electrodes formed on the upper surface of said stepped level-difference, based on results of a detection conducted from above the package to recognize a boundary formed by said stepped level-difference and inner bottom surface for at least two;

a second step for mounting said chip in the inside of said package;

a third step for determining a spot for bonding an interconnection wire to connect said internal contact electrode and said chip, based on results of a detection conducted from above said package to recognize a boundary formed by said stepped level-difference and inner bottom surface for at least two;

a fourth step for electrically connecting said chip and said internal contact electrode with the interconnection wire; and

a fifth step for sealing an opening of said package with a lid.

15. (Original) The method for manufacturing electronic components recited in claim 14, which electronic components having a shield electrode on the inner bottom surface of the package and a non-shielded electrode portion, which region is disposed in an arrangement where one of the sides, or the extension, crosses with one of the sides of said internal contact electrode, or the extension, at a right angle as viewed from above said package; in the first step wherein,

a place for mounting the chip is determined by detecting a cross point formed by one of the sides of said non-shielded electrode portion, or the extension, and one of the sides of said internal contact electrode, or the extension, for at least two; and in the third step wherein,

a spot for bonding the interconnection wire is determined by detecting a cross point formed by one of the sides of said non-shielded electrode portion, or the extension, and one of the sides of said internal contact electrode, or the extension, for at least two.

16. (Previously Presented) The electronic component of claim 2, wherein said non-electrode portion is provided for at least two, and said chip is disposed on said shield electrode in a place connecting said two non-electrode portion .

17. (Previously Presented) The electronic component of claim 2, wherein one of the sides of said non-electrode portion substantially and one of the sides of said internal contact electrode substantially coincide on a straight line.

18. (Previously Presented) The electronic component of claim 2, wherein one of the sides of said internal contact electrode and one of the sides of said non-electrode portion cross at substantially a right angle, as viewed from the above.

19. (Previously Presented) The electronic component of claim 2, wherein clearance between the stepped level-differences in the package's inner wall surface is greater in the lower part than in the upper part.

20. (Previously Presented) The electronic component of claim 2, wherein the upper surfaces of internal contact electrode and chip are substantially on a same plane.

21. (Previously Presented) The electronic component of claim 2, wherein the length of a non-shielded electrode portion along a direction connecting the internal contact electrode and the chip is greater than the value of focus shift margin of a lens used for recognizing a boundary between said internal contact electrode and non-shielded electrode portion.

22. (Previously Presented) The electronic component of claim 2, wherein a side, facing the internal contact electrode, of the non-shielded electrode portion has a length that is greater than the value of a gap between the internal contact electrodes.